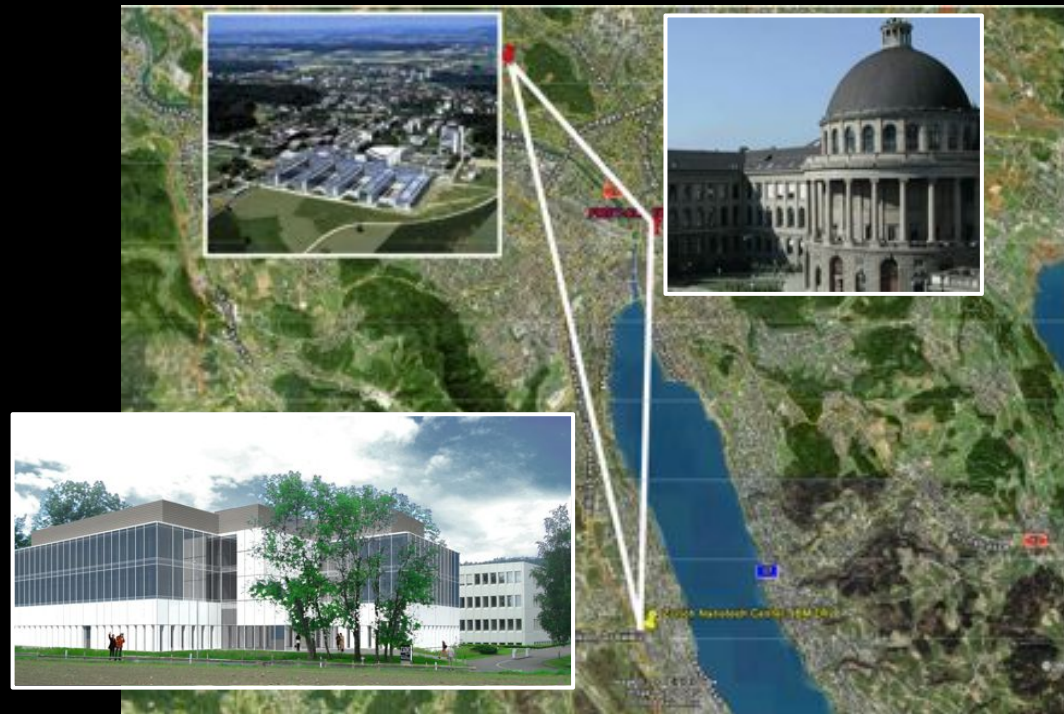


# Nanoelectronics Across the Zurich Lake

IBM Research – ETH Zurich  
Nanoscale Exploratory Technology Lab

Plastic Optoelectronics Workshop  
Basel, Switzerland  
June 25, 2010



# Nanoscale Exploratory Technology Laboratory (NETL)



A unique public-private partnership between IBM and the Swiss Federal Institute of Technology (ETH Zürich)

# The Nanoscale Exploratory Technology Laboratory

- **A unique facility for exploratory research not available elsewhere**
  - Not a production or a pilot line with fixed processes and fixed wafer size
  - Exploratory clean room fabrication capability combined with ultra-isolated, noise-free labs
- **Unique skills and expertise at the Zurich Research Lab**
  - One of the birthplaces of nanotechnology: Nobel Prizes in physics for the scanning tunneling microscope in 1986 and high-temperature superconductors in 1987
- **Leveraging IBM's presence in Europe**
  - Leading talent in nanotechnology, major government initiatives
  - One third of world-wide investment in nanotechnology (\$Bs over the next 5 years)
- **Partnerships to contain depreciation and operation costs**
  - Existing examples: IBM CMOS alliance, Albany Nanotech
  - ETH Zurich is primary partner at ZRL
  - **Additional partners welcome!**

# The Cooperation Model

Leading-edge science requires a leading-edge infrastructure –  
at NETL industry and academia are creating it together.



- IBM constructs building (\$60 M)
- Cleanroom operated by IBM personnel
- ETH leases space (cleanroom, offices, off-line labs)
- ETH contributes to operating costs
- Capital equipment costs shared between ETH and IBM (\$30 M)
- ETH professorships located at NETL
- Contract for a minimum of 10 years
- Both joint and individual research projects

- **ETH #1 technical university in Europe**
  - 14000 students
  - 6300 staff
  - 21 Nobel laureates
  - \$1.2B annual budget

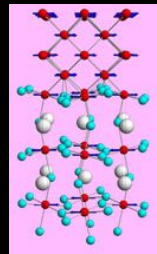
What kind of research are we doing?



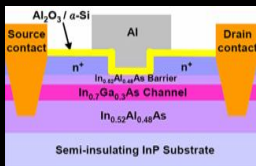
# Nanoscale Devices for Information Processing

## Nanoelectronics

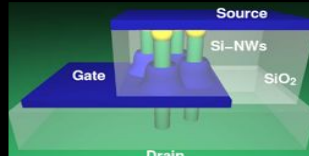
## Beyond Charged-Based Logic



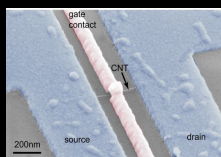
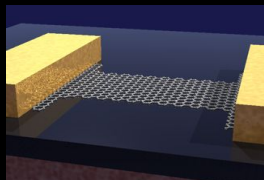
### Materials for future CMOS



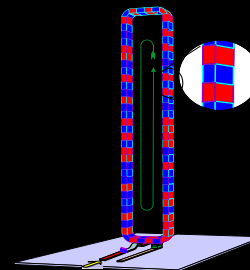
### Semiconductor Nanowires



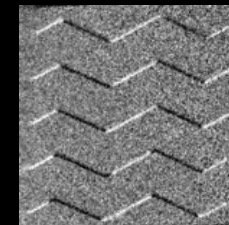
### Storage-Class Memory



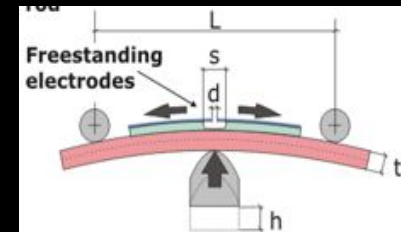
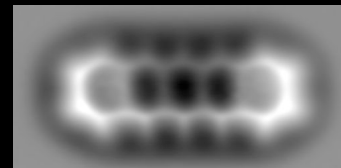
### Carbon-based devices



### Spintronics



### Molecular electronics

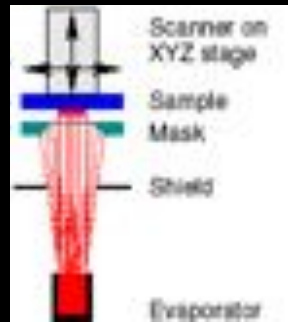


### Quantum devices

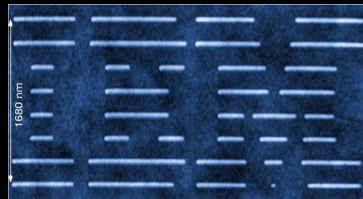


# Nanotechnology for Electronics

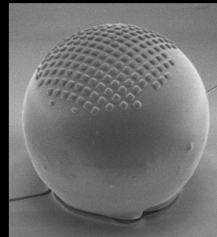
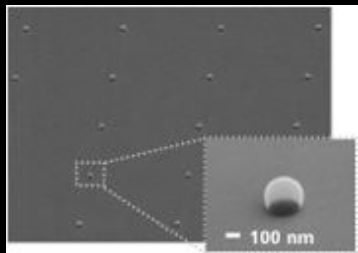
## Nanofabrication



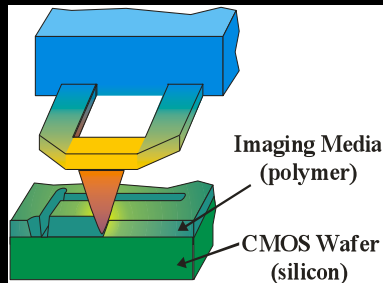
### Nanostencil Lithography



## Directed Self-Assembly Platform



## Probe-based Lithography



## Sensors and Actuators

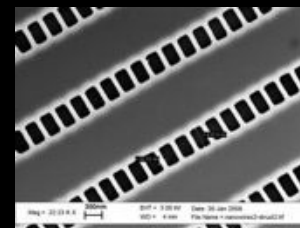
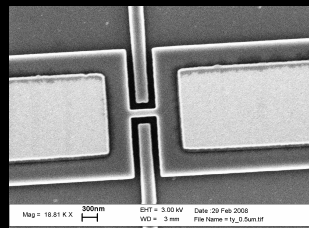
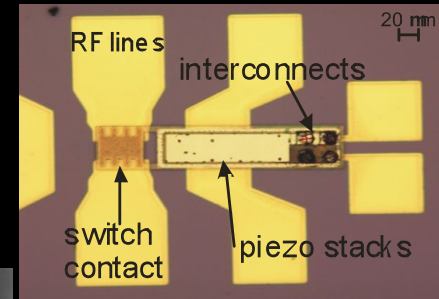
### Carbon Electronics for Sensors



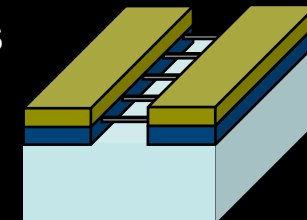
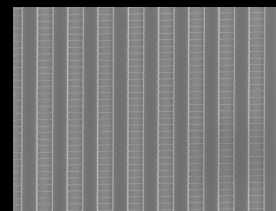
### Graphene Nanoribbons



### CMOS Integration of MEMS/ NEMS Sensors and Actuators



### Silicon Nanowire Sensors



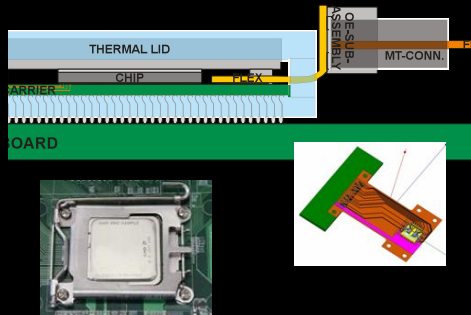
# Photonics

Optical Interconnects

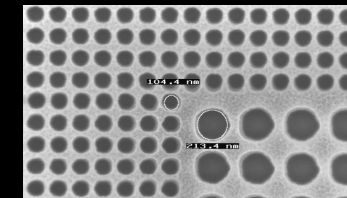
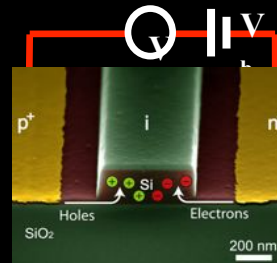
Integrated Si Photonics

New Materials/Devices

Optics to the carrier

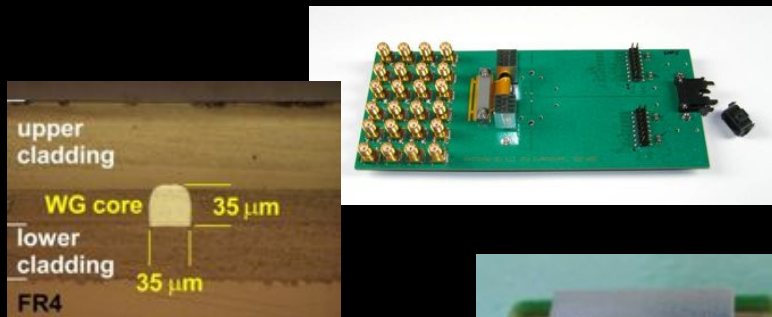


Modulators

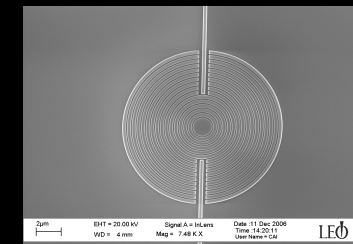
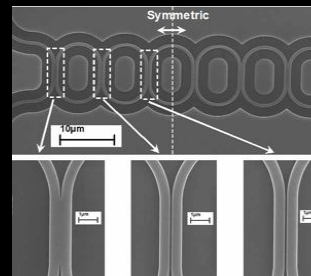


Photonic Bandgap Structures

Polymer Waveguides

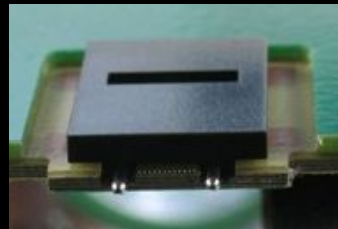


Switches



All Optical Switches

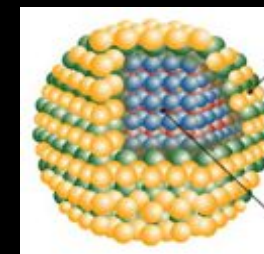
Passively-aligned Optical Connectors



(De-)Multiplexing



Non-linear Materials





# Energy

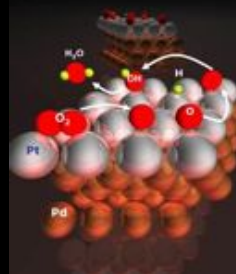
## Generation

Concentrator Photovoltaic Devices



## Storage

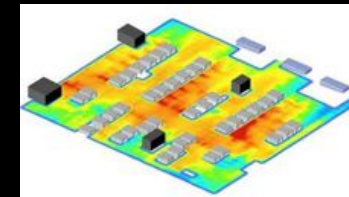
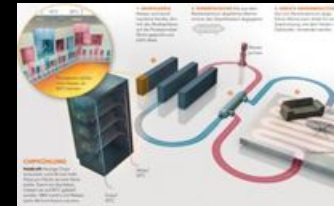
High Energy Density Batteries



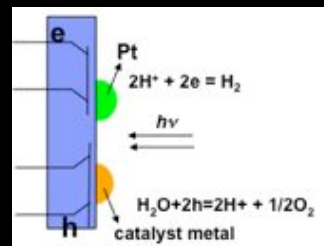
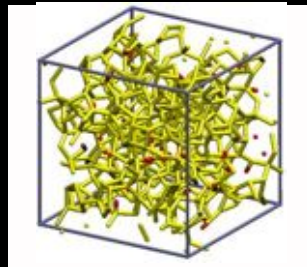
High Energy Density Batteries

## Conservation

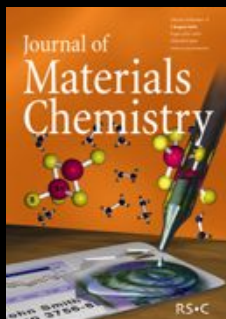
Zero Emission Data Center



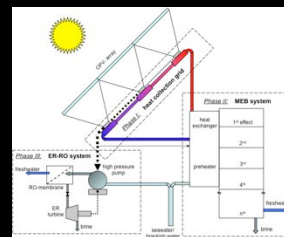
Modelling



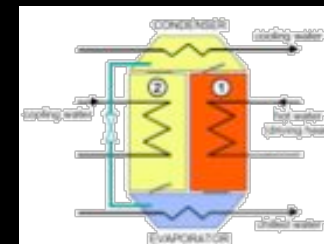
Photocatalysis



Organic & Hybrid Photovoltaic devices



Energy Reuse For Desalination

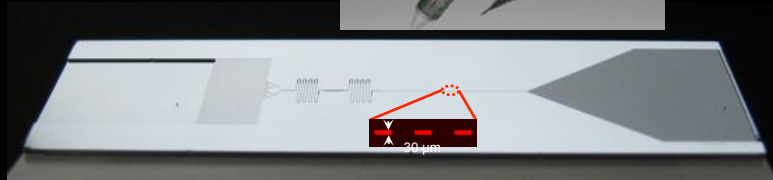
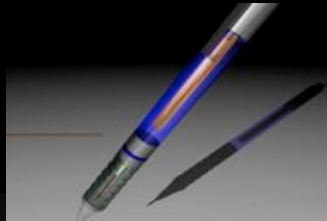


Solar Driven Adsorption Chiller

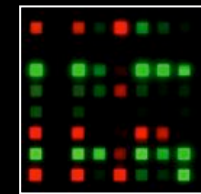
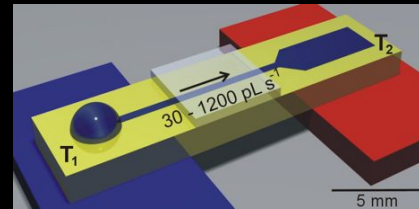
# Health Care / Life Sciences

## Microfluidics, Sensing, Simulations

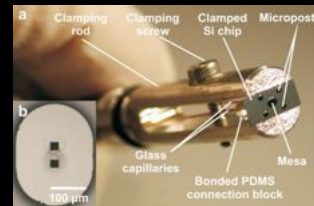
### Point-of-Care Diagnostics



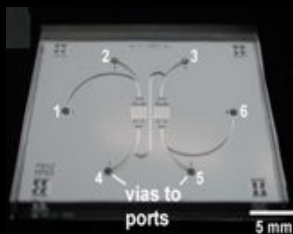
### Micromosaic Immunoassays



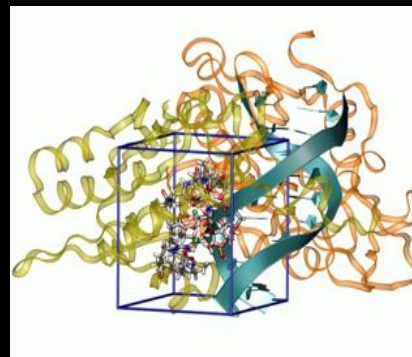
### Microfluidic Probe



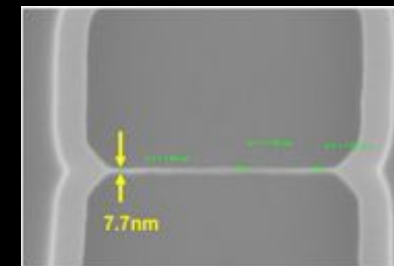
### Brain Chip



### Modeling



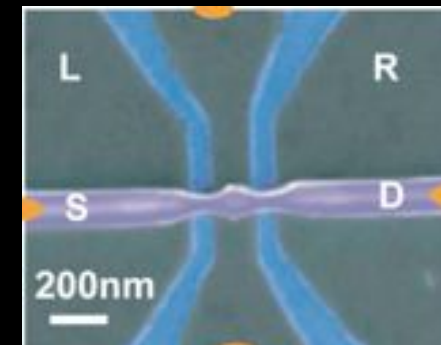
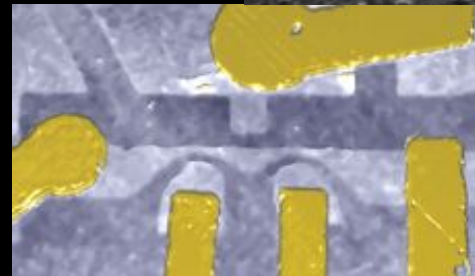
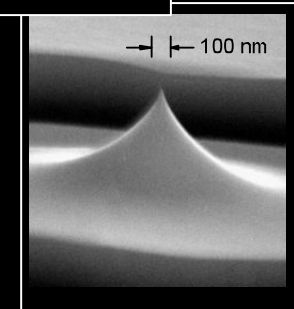
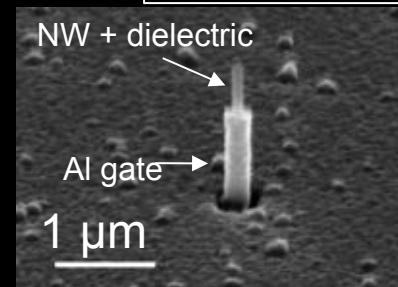
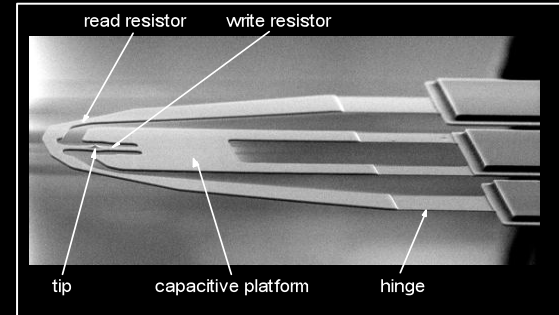
### Carbon Nanotube Sensors



# The Infrastructure

# Identified technologies

- MEMS/NEMS
- Spintronics/Magnetism
- Nanowires
- Carbon-based devices
- Organic electronics
- Functional materials
- Directed self-assembly
- Packaging for
  - Thermal management
  - 3D integration
  - Optical interconnects
- Photonics
- Nanobiology
- Simulation and theory



# Process capabilities

- Most processes will be semiconductor based (Silicon, III/V)
- Materials similar to those used in standard semiconductor technology (Si, metals, isolators, polymers, organics, oxides, ...)
- No fixed wafer size, flexibility is important, maximum 6 inch
- Not a manufacturing/pilot line, but a lab for exploratory research
- Cleanroom class 100/1000 is good enough
- Small effort on biology planned, no biology in cleanroom



# Cleanroom processes/equipment

## Tools/process sectors

- Lithography
  - Pattern definition
- Wet processing
  - Substrate cleaning, wet chemical etching
- Thin film deposition
  - Metals, isolators, ...
- Dry etching
  - Material removal using (reactive) gases
- Thermal processing
  - Oxidation, annealing, vapor phase deposition
- Metrology/inspection
  - Optical and electron microscopes, surface topology
  - Thickness measurements, ...
- Backend
  - Plating, lapping/polishing, dicing, bonding
- IBM sector
  - Polymer waveguide processing for optical interconnects

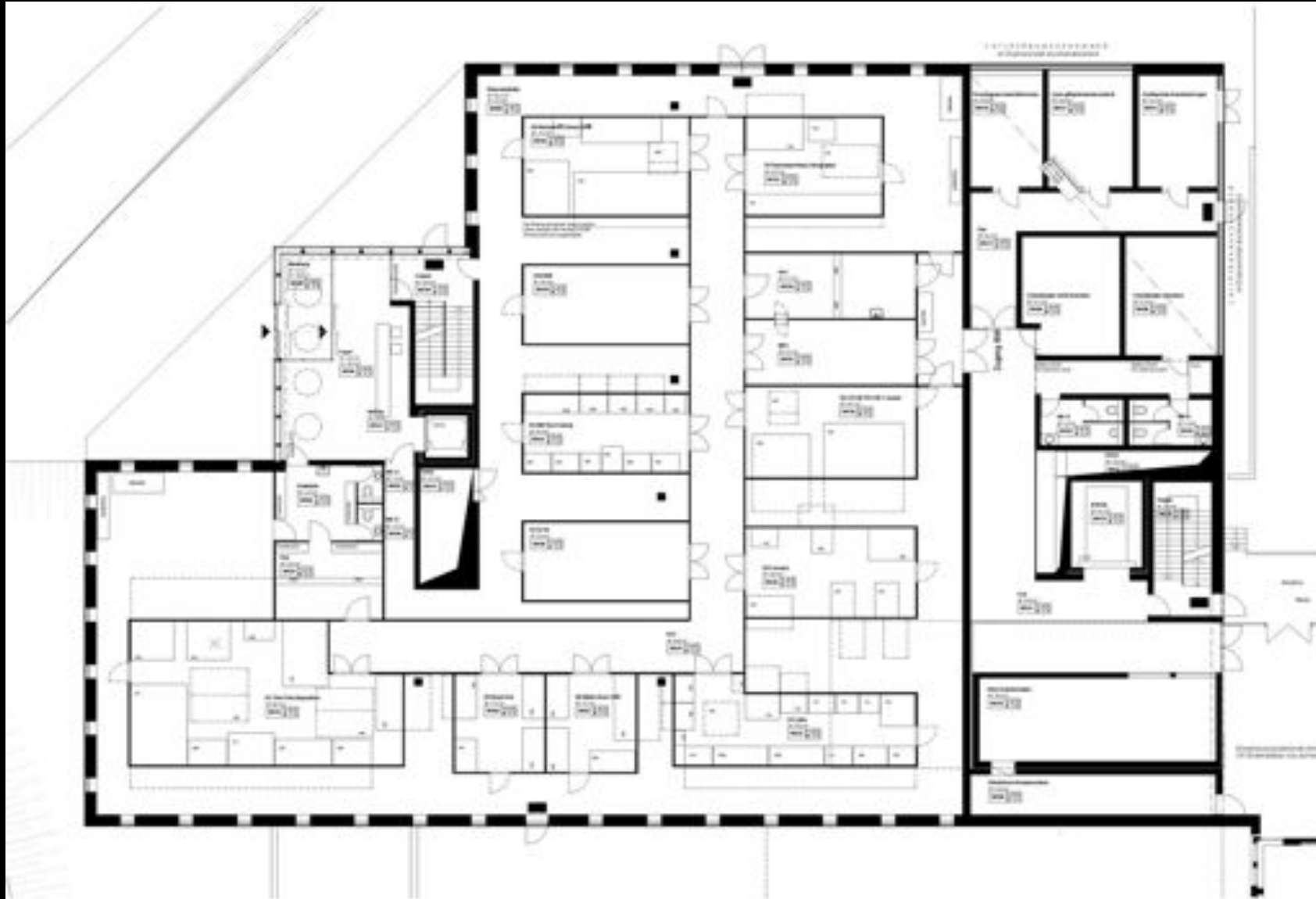


## The Building



- New clean room ~ 950 m<sup>2</sup>
- Noise-free laboratories
- Off-line labs and offices
- Total floor space ~ 6'000 m<sup>2</sup>

# Level 1: Cleanroom, chemical storage, partner entrance



## Level 0: Noise-free Labs

### Ultrastable labs for sensitive tools

#### Goals:

- Mechanical vibrations:  
0.5  $\mu\text{m/s}$  (x,y), 5  $\text{nm/s}$  (z) below 16 Hz
- Acoustic noise:  $<50 \text{ dBc}$  ( $<55 \text{ dBc} / f > 100\text{Hz}$ )
- Electromagnetic fields:  $B < 5 \text{ nT}$
- Temperature: 0.1 C/h

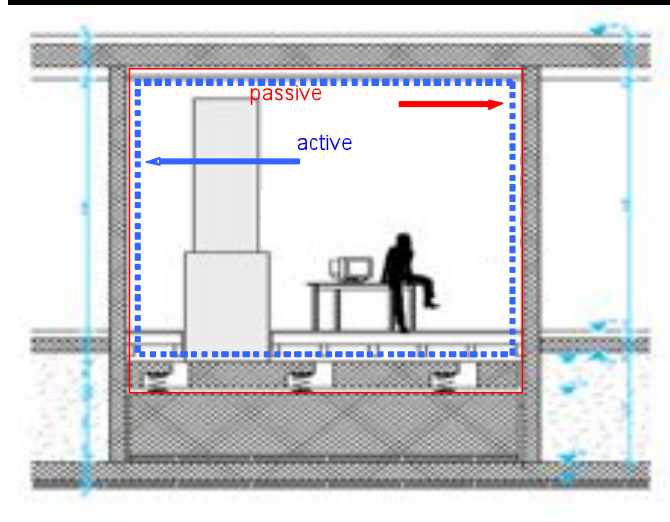
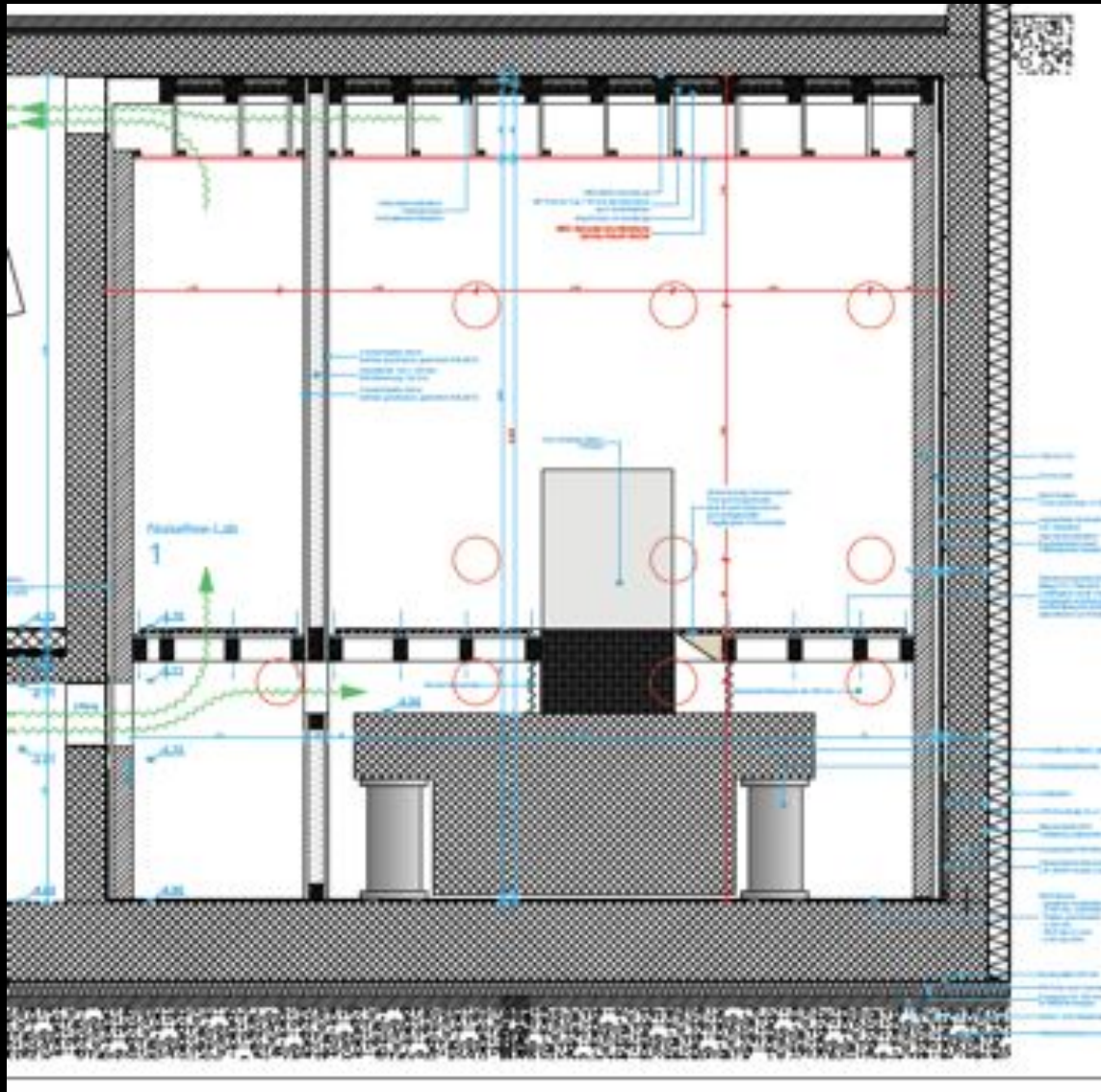
#### Measures:

- Passive mechanical damping,  $f > 2\text{Hz}$
- Active mechanical damping,  $f = 0.5 - 0.8 \text{ Hz}$
- Passive EM shielding (Faraday cage), 20 nT
- Helmholtz coils with active compensation for  $B < 20 \text{ nT}$





# Noise-free Labs





# Building status June 24, 2010



[www.zurich.ibm.com/net/](http://www.zurich.ibm.com/net/)

Thank you for your attention.

*Additional partners welcome!*



Contact information:

Paul Seidler

[pfs@zurich.ibm.com](mailto:pfs@zurich.ibm.com)